

# Summary

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- Stato delle gare in corso.
- Fondi da sbloccare nel 2019
- Spese previste nel 2020.
- Aggiornamento sul raffreddamento del calorimetro.
- Aggiornamento sul cilindro interno di carbonio.

# Stato delle gare

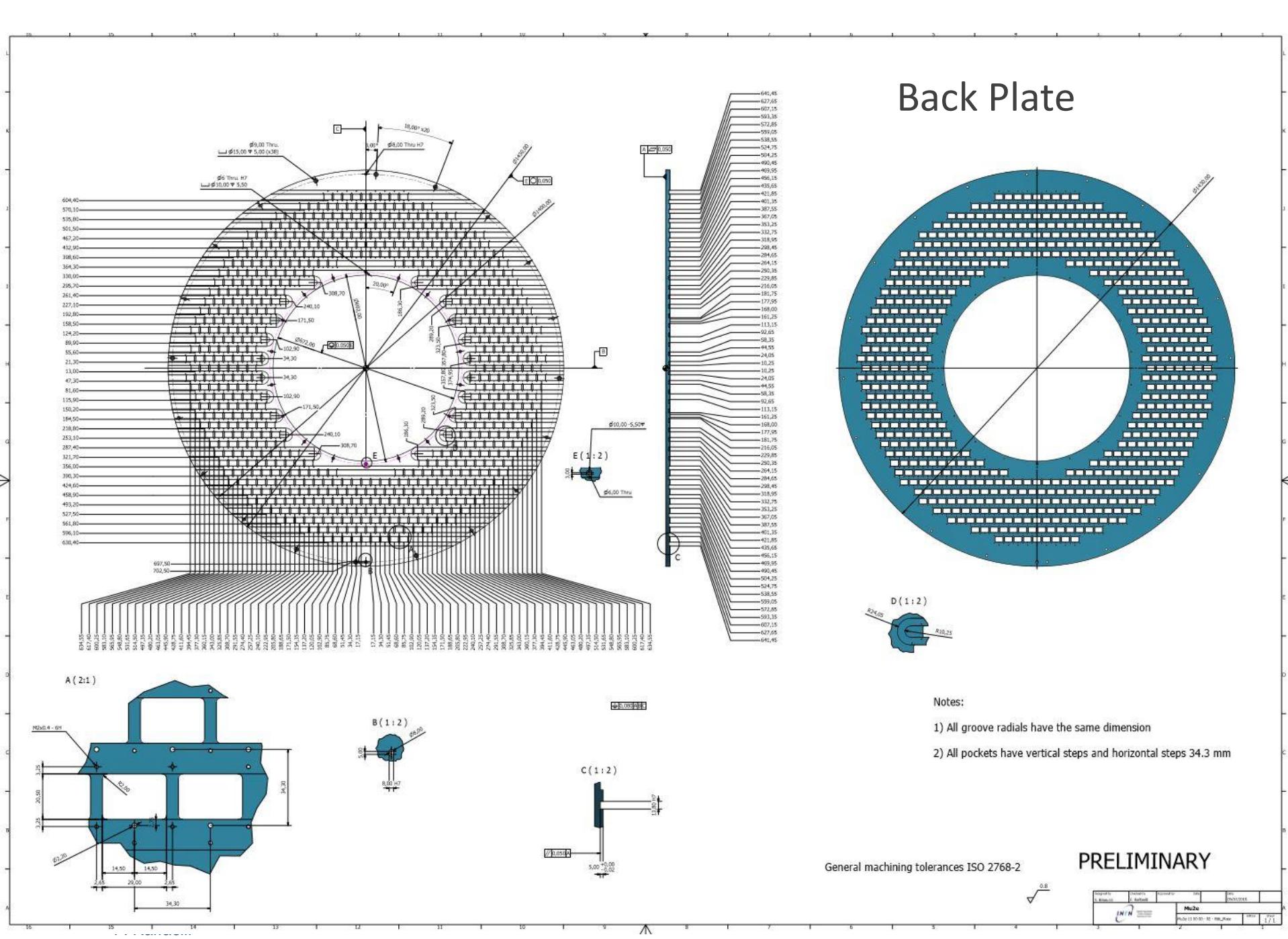
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- Tre gare sono state completate;
- I due piani in peek di back end.
- linee di raffreddamento in rame compreso di collettori e l'integrazione di esse sul piano di back end.
- La gara dei crate e dei collettori

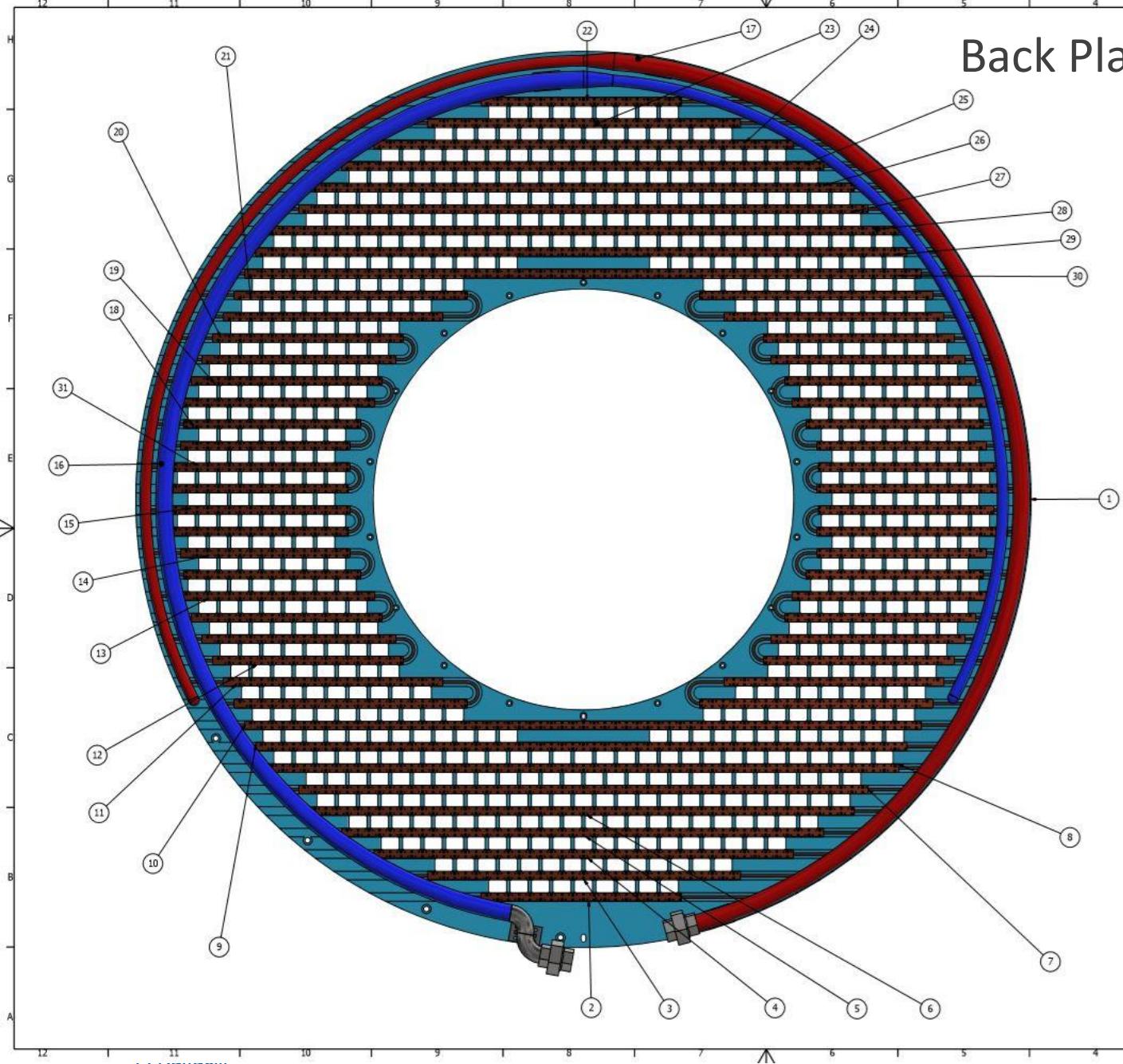
La situazione e' la seguente I risultati delle gare sono state approvate dalla giunta in Luglio. L'amministrazione centrale deve stipulare i contratti. Ho delegato Bruno Quarta per la verifica dei requisiti delle ditte il 26 Agosto 2019.

Sono previste 6 mesi per le consegne dal momento della stipula del contratto e dal rilascio dei disegni eseguivi.

# Back Plate



# Back Plane



ELENCO PARTI		
ELEMENTO	QTA	NUMERO PARTE
		DESCRIZIONE
1	1	Mu2e_11_00_00 - 02 - Plate PROVA_01
2	1	Mu2e_M2-0200 - Canale_01
3	1	Mu2e_11_04_00 - 00 - Cooling_Channel_02
4	1	Mu2e_11_05_00 - 00 - Cooling_Channel_03
5	1	Mu2e_11_06_00 - 00 - Cooling_Channel_04
6	1	Mu2e_11_07_00 - 00 - Cooling_Channel_05
7	1	Mu2e_11_08_00 - 00 - Cooling_Channel_06
8	1	Mu2e_11_09_00 - 00 - Cooling_Channel_07
9	1	Mu2e_11_10_00 - 00 - Cooling_Channel_08
10	1	Mu2e_11_11_00 - 00 - Cooling_Channel_09
11	2	Mu2e_11_12_00 - 00 - Cooling_Channel_10
12	2	Mu2e_11_13_00 - 00 - Cooling_Channel_11
13	2	Mu2e_11_14_00 - 00 - Cooling_Channel_12
14	2	Mu2e_11_15_00 - 00 - Cooling_Channel_13
15	2	Mu2e_11_16_00 - 00 - Cooling_Channel_14
16	1	Mu2e_11_01_00 - 00 - FEE_Manifold
17	1	Mu2e_11_02_00 - 00 - FEE_Manifold
18	2	Mu2e_11_15_00 - 00 - Cooling_Channel_13_MIR
19	2	Mu2e_11_14_00 - 00 - Cooling_Channel_12_MIR
20	2	Mu2e_11_13_00 - 00 - Cooling_Channel_11_MIR
21	2	Mu2e_11_12_00 - 00 - Cooling_Channel_10_MIR
22	1	Mu2e_11_11_00 - 00 - Cooling_Channel_09_MIR
23	1	Mu2e_11_04_00 - 00 - Cooling_Channel_02_MIR
24	1	Mu2e_11_05_00 - 00 - Cooling_Channel_03_MIR
25	1	Mu2e_11_06_00 - 00 - Cooling_Channel_04_MIR
26	1	Mu2e_11_07_00 - 00 - Cooling_Channel_05_MIR
27	1	Mu2e_11_08_00 - 00 - Cooling_Channel_06_MIR
28	1	Mu2e_11_09_00 - 00 - Cooling_Channel_07_MIR
29	1	Mu2e_11_10_00 - 00 - Cooling_Channel_08_MIR
30	1	Mu2e_11_11_00 - 00 - Cooling_Channel_09_MIR
31	2	Mu2e_11_16_00 - 00 - Cooling_Channel_14_MIR

Created by: F. Raffaelli      Checked by:      Approved by: Date: 05/07/2018

INN	Mu2e
Mu2e II - 08-09 - 08 - RFE_Cooling_Plane	Version: 1/1

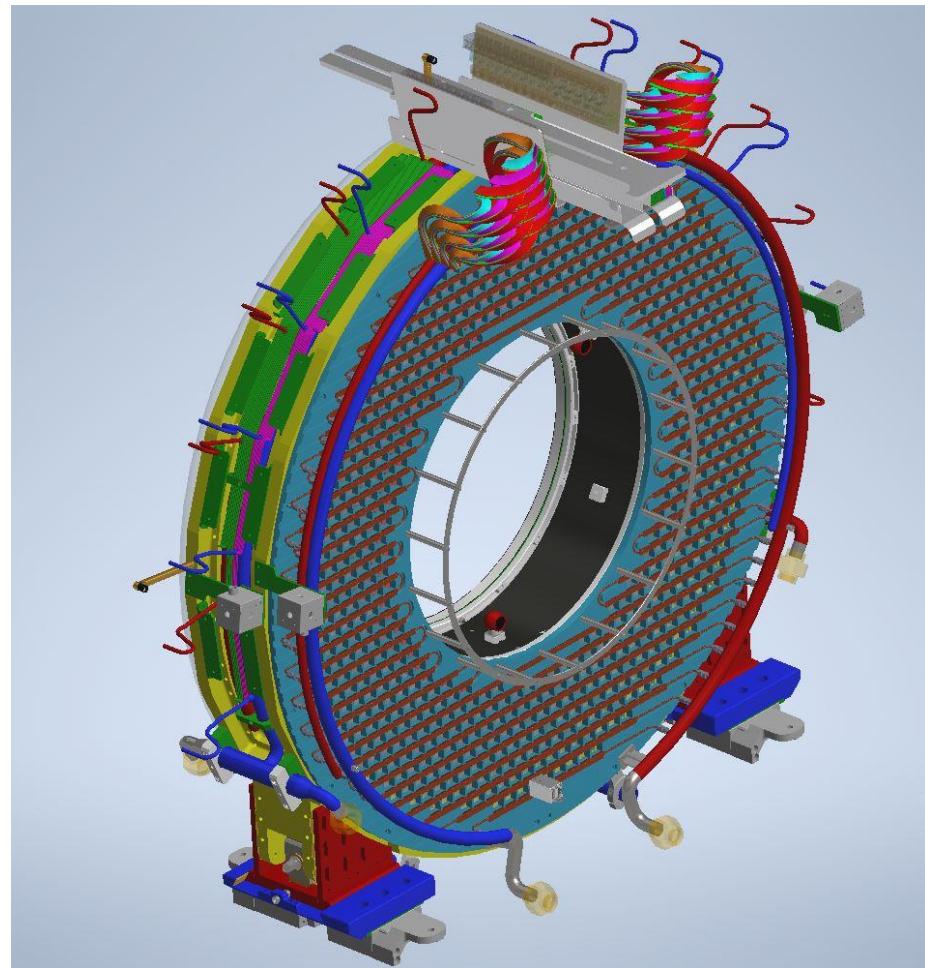
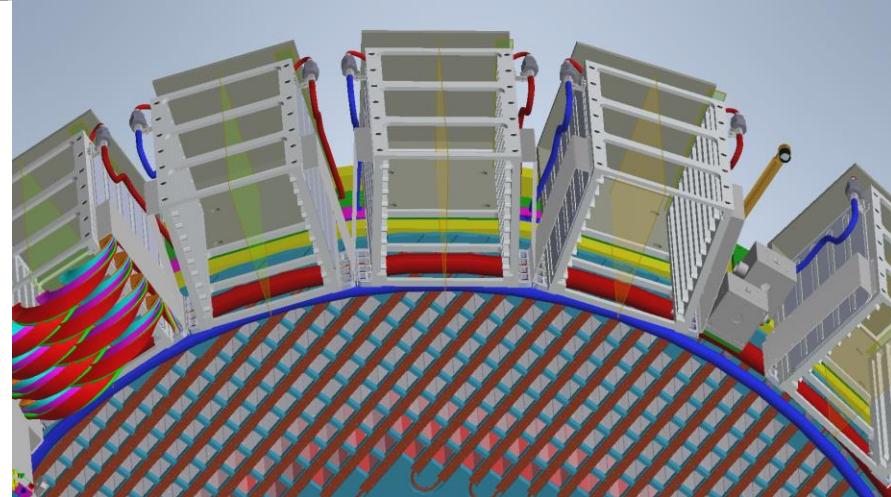
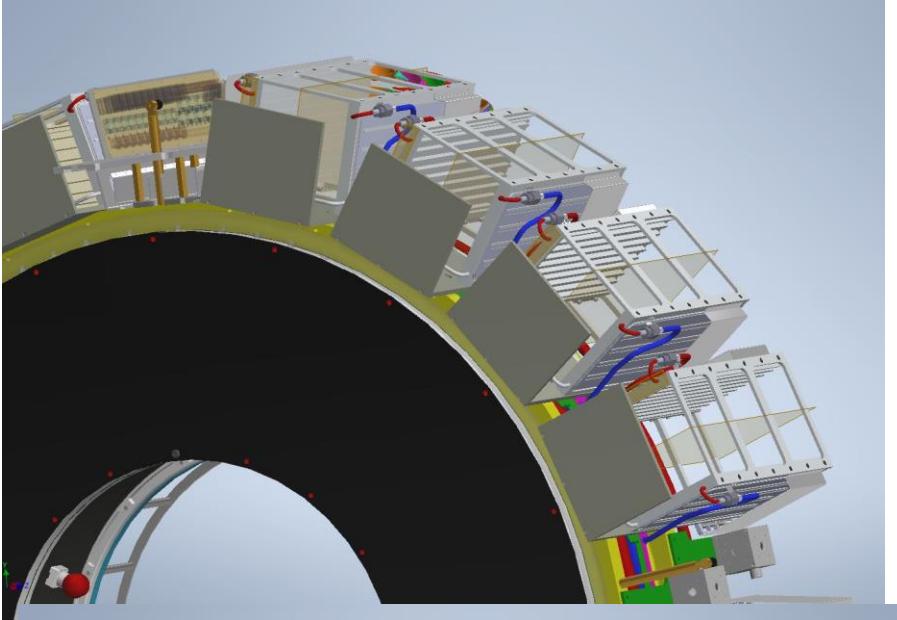


## Fondi da sbloccare nel 2019

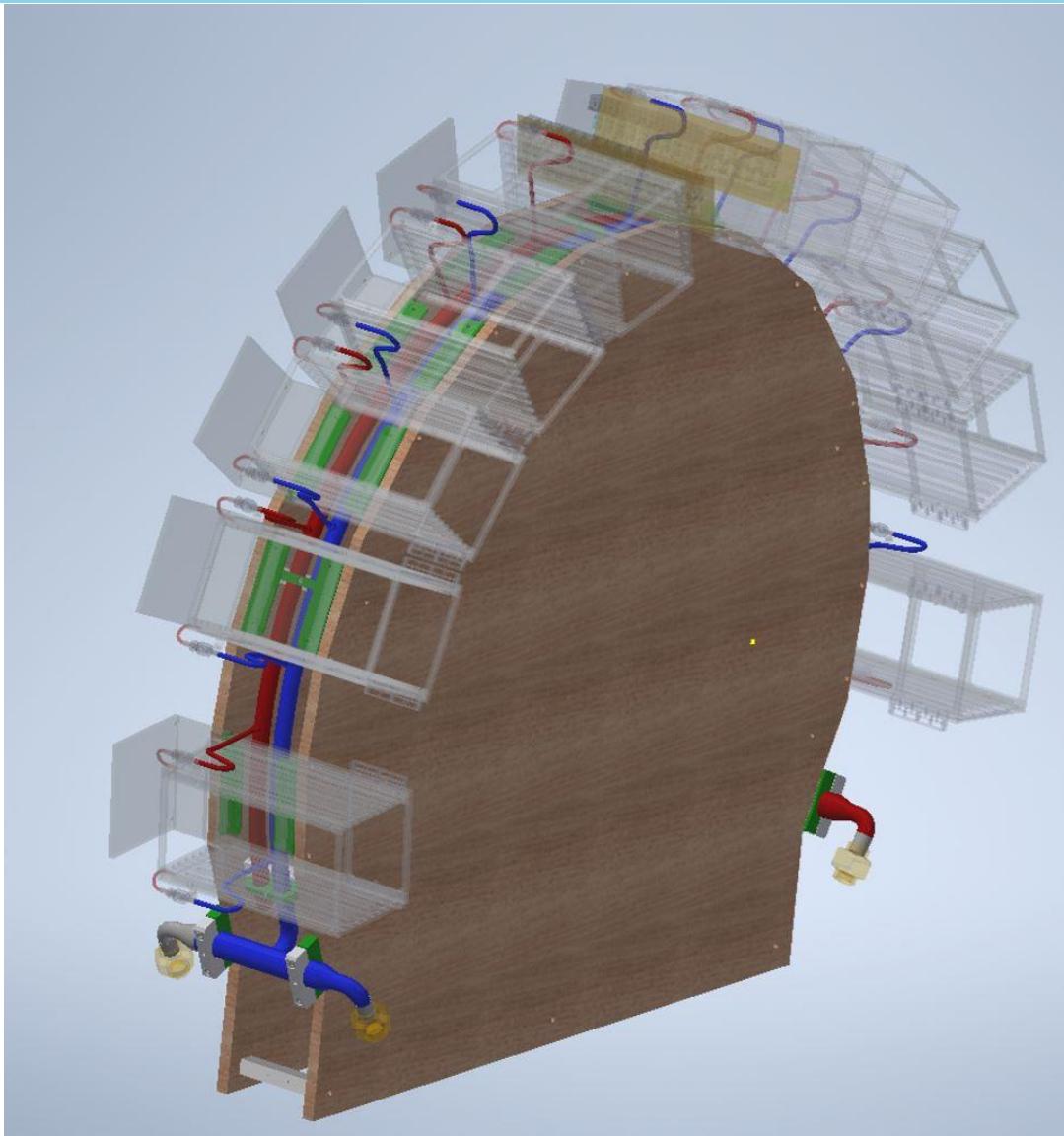
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- Mock-up per la costruzione dei manifolds 4 Keuro
- Alette e support crate in G10 7 Keuro.
- Atrezzatura di trasporto del back plane 2 Keuro

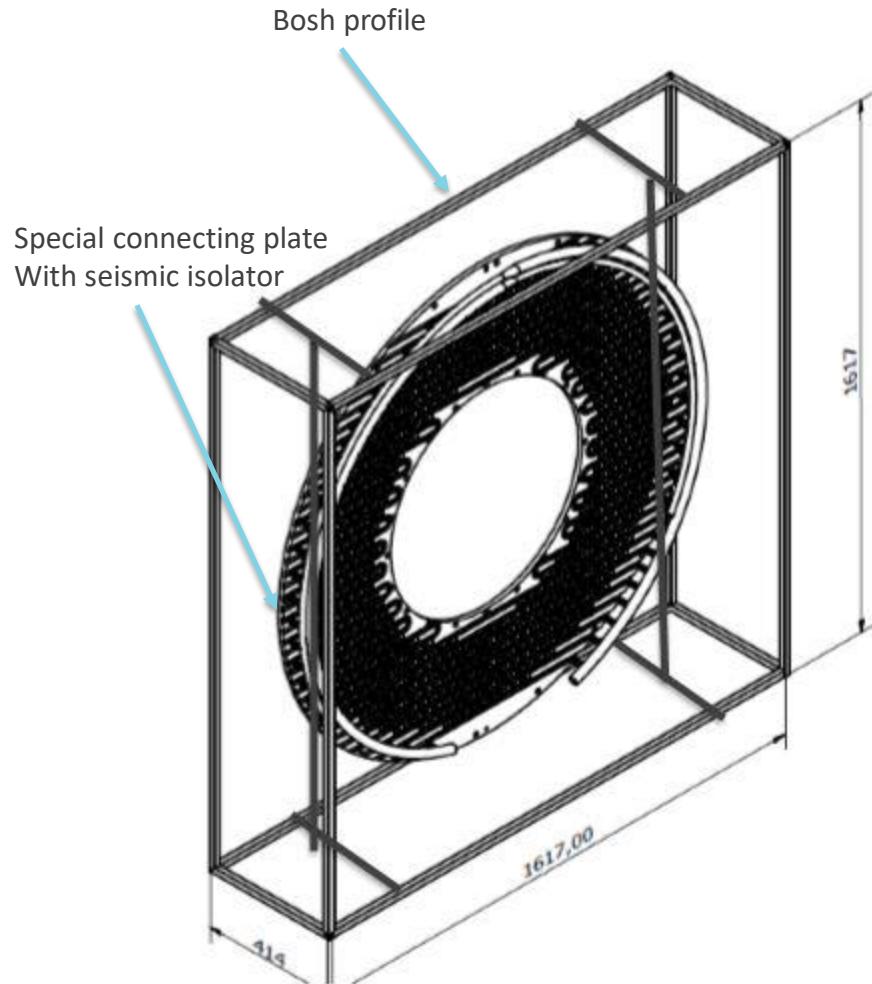
# Mockup collettori e alette di supporto



# Mockup collettori e alette di supporto



## Attrezzatura di trasporto del back plane.



Mass 100 kg

Dimensions need to be compatible with air transportation.

The external bag can be dismount leaving the back plane on his support with the internal bag. This will be removed at the time of installation on the ring. Sufficient space need to store and perform the handling operations.

# Spese previste 2020

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- 1) Attrezzature leak test back plane e crates 15 Keuro.
- 1) Sistema di raffreddamento per test a Fermilab per il front end.  
(chiller pompa ausiliaria valvole di controllo e di isolamento, flow meter Filtri, sensori di pressione etc.) 15Keuro.

# Aggiornamento sul raffreddamento del calorimetro.

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- Mechanical Review at Fermilab 21-05-2019

The mu2e calorimeter group has proposed to improve the calorimeter SiPM reliability in the final period of operation, reducing the SiPM max operating temperature.

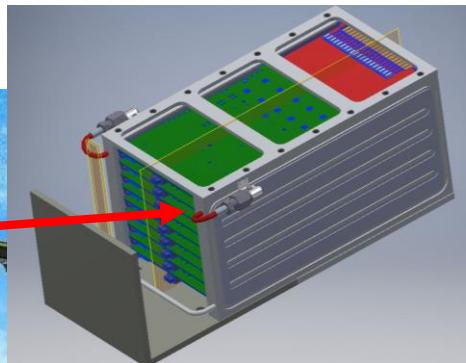
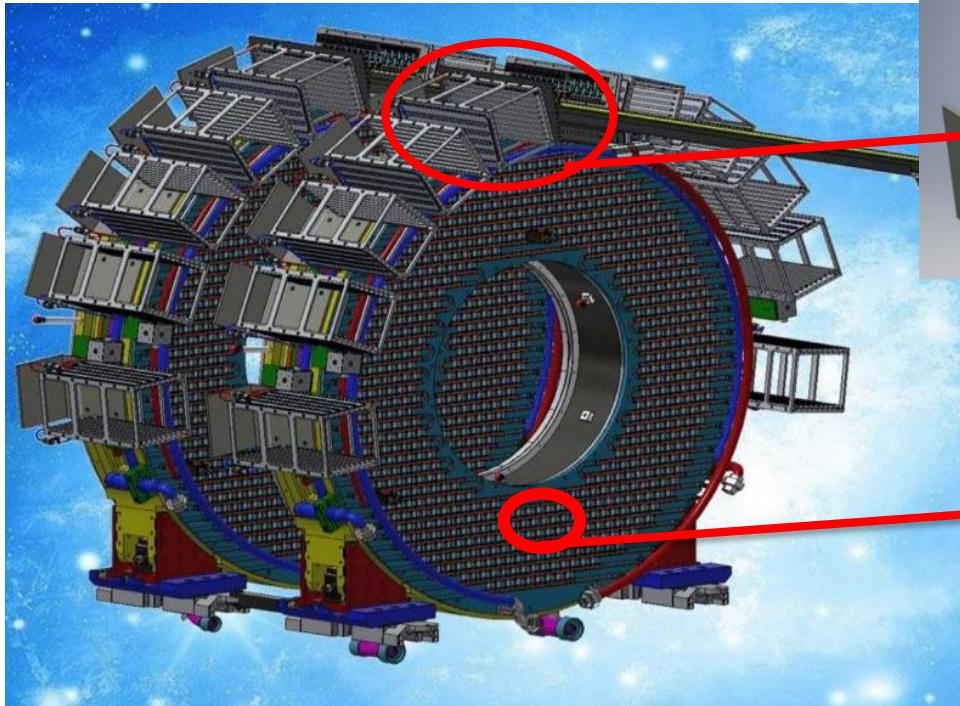
- The max allowed temperature has been set to 0-degree C for a long period of time. Now knowing better the SiPM behavior under radiation and considering the uncertainties on the effective dose absorbed, we consider prudent to have the possibility to operate the SiPM at -10 degree C.

- The implications of lowering the temperature has been preliminary analyzed thermally and mechanically. The first thing to do, is to reconsidered the secondary fluid. Etc,Etc, Etc.

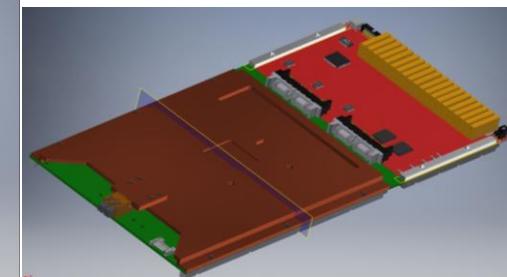
Thanks Fabrizio Raffaelli

# Cooling system overview

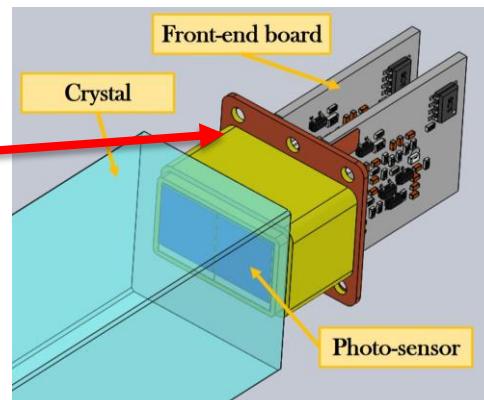
- The power dissipated are in two main areas:
- on the Back plate (SIPMs and pre-amplifiers)
- on the outside perimeter of the calorimeter ring (10 DAQ crates).



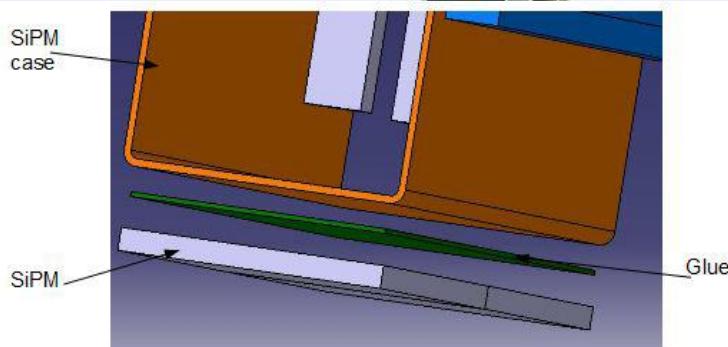
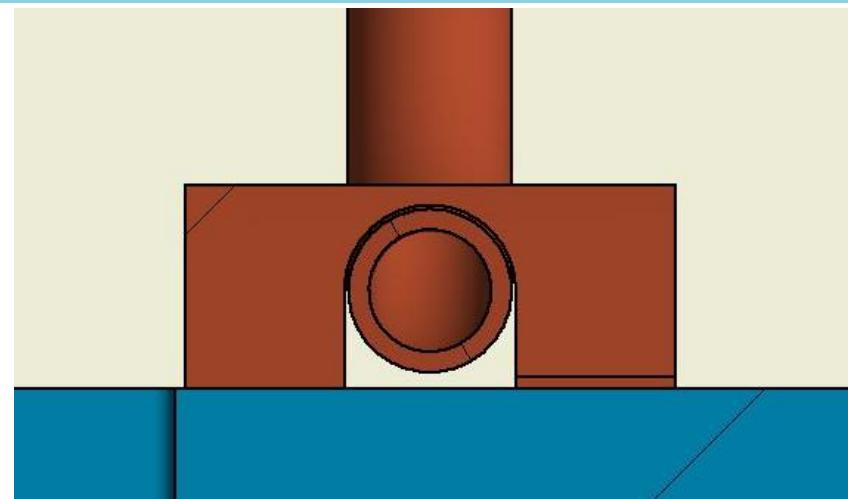
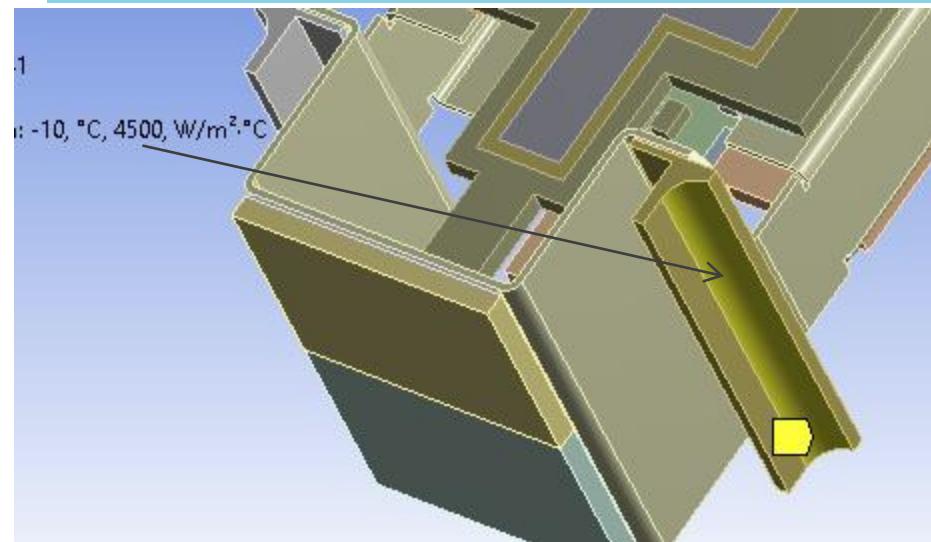
Dirac and mezzanine



Front-end

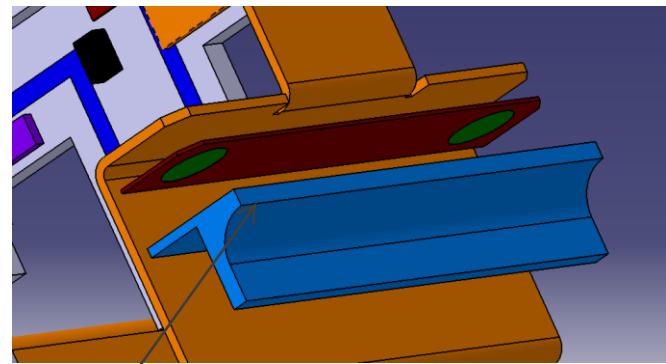


# Mu2e SiPM FEM details



The pressure is assure by M2.5 property class 70 that can be preload at 250 Newton considering that the thread is on cooper. So an average pressure di 25 Mpa  
 $R_{int}=0.01 \text{ m}^2 \text{ k/kwatt}$

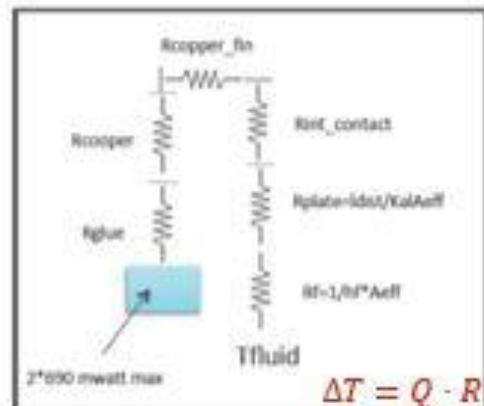
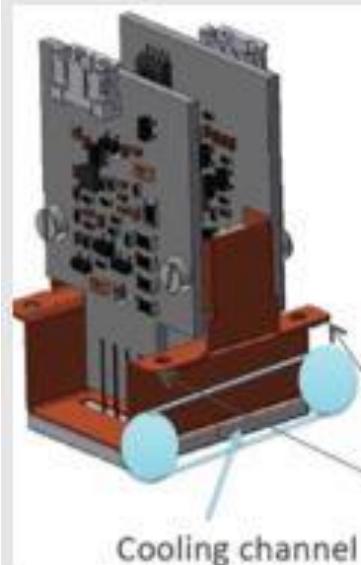
Realist model respected the adopted solution



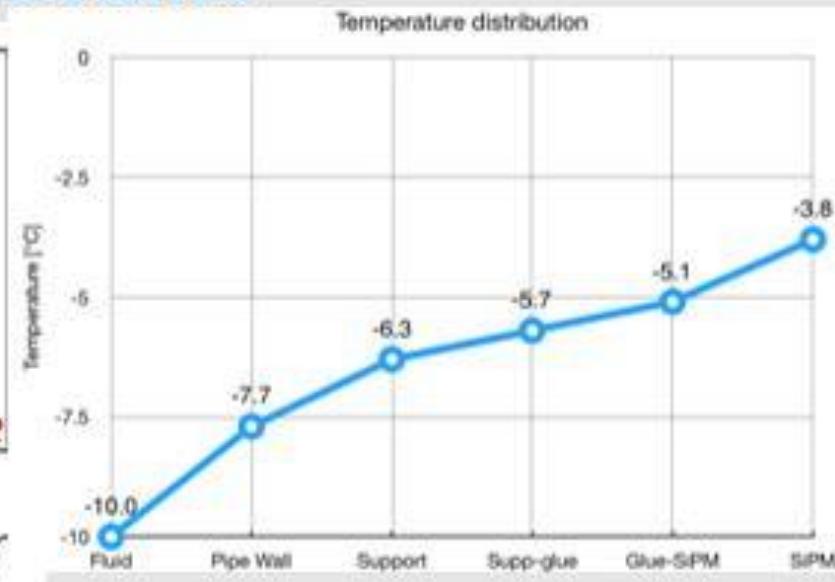
Gasket to simulate the thermal contact

# Aggiornamento sul raffreddamento del calorimetro.

## Thermal resistance



Contact length 28mm



From earlier simulation the temperature difference between fluid and SPM is around 6.3 °C

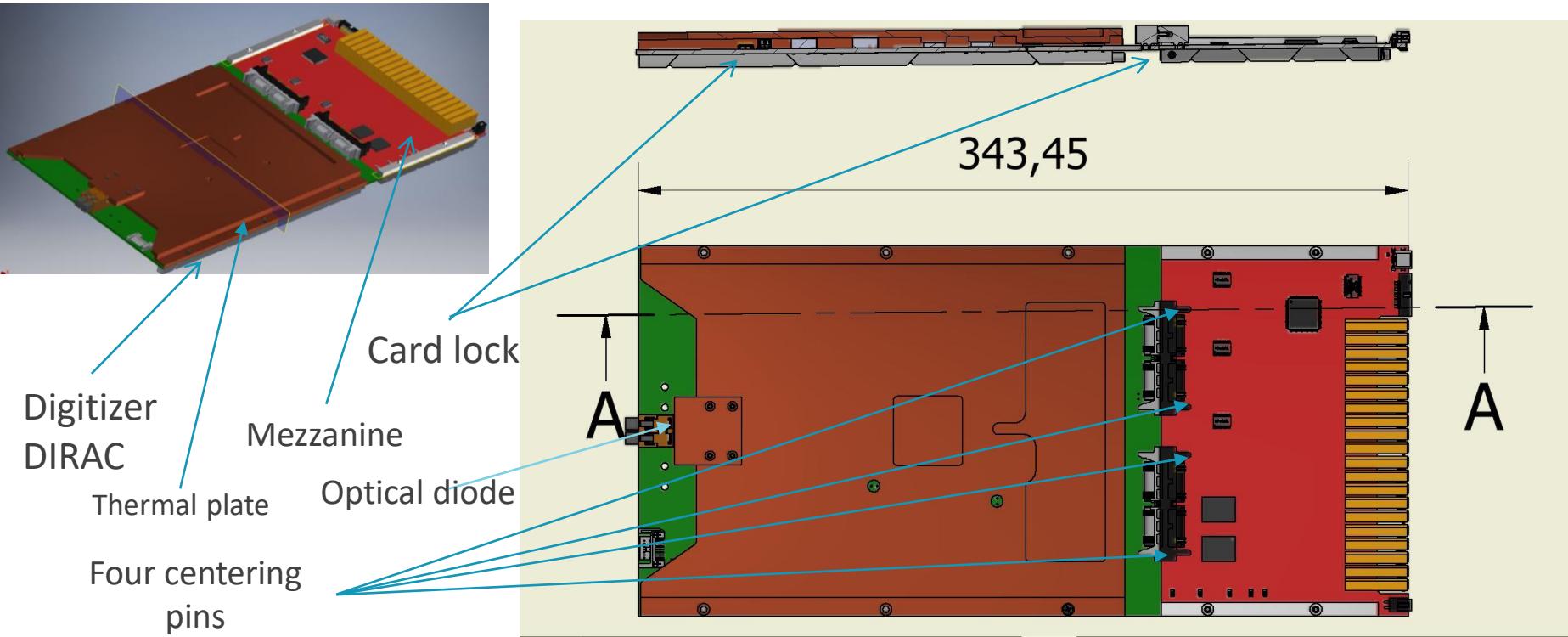
Set point of the fluid temperature at SPM location.  
 $T_{fl} = -20$  °C

Maximum  $\Delta T = 2.6$  °C  
 $m_{tot} = \frac{Q}{c_p \Delta T} = 4.8 \text{ kg/s}$

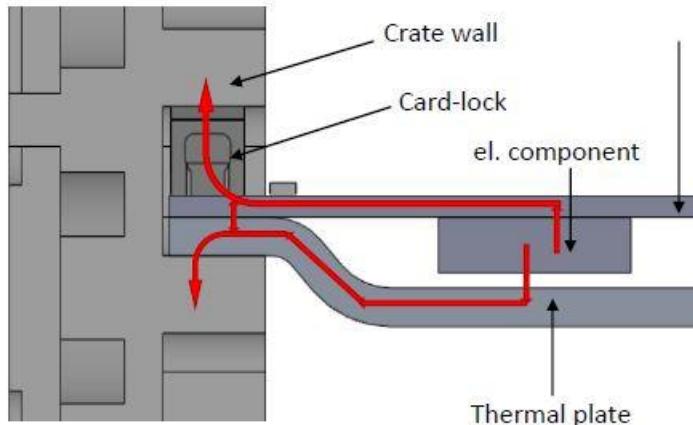
FEM analysis qualify with experimental data

# A compact crate with 9 board slots

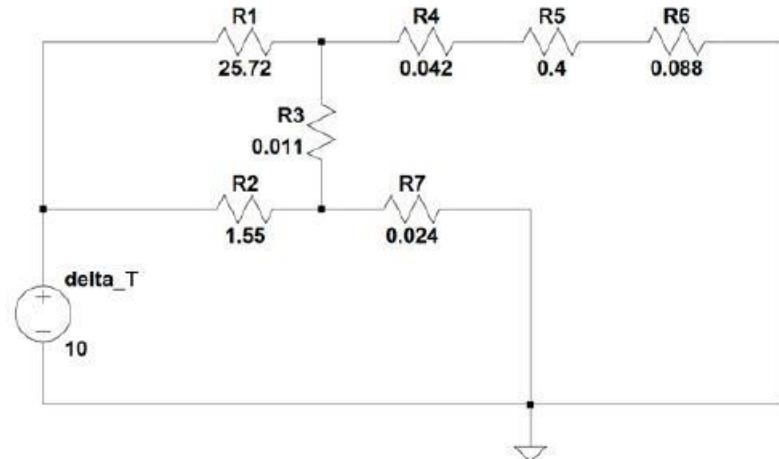
- The crates house the electronic boards and provide their cooling.
- Mechanical issues:
  - The available space is quite limited.
  - The space for the insertion and extraction of the cards does not allow to have a single card.



# Board cooling



EQUIVALENT THERMAL CIRCUIT



R1: thermal resistance between the junction and the edge of thermal plate

R2: thermal resistance between the junction and the edge of the board

R3: thermal resistance due to the contact (Cu-Cu) between the board and the thermal plate

R4: thermal resistance due to the contact (Cu-Al) between the board and the card-lock

R5: Internal thermal resistance of the card-lock

R6: thermal resistance due to the contact (Al-Al) between the card-lock and the crate wall

R7: thermal resistance due to the contact (Cu-Al) between the thermal plate and the crate wall

# Crate cooling.

The first prototype of DIRAC has been available. We were able to do a realist thermal test on it.

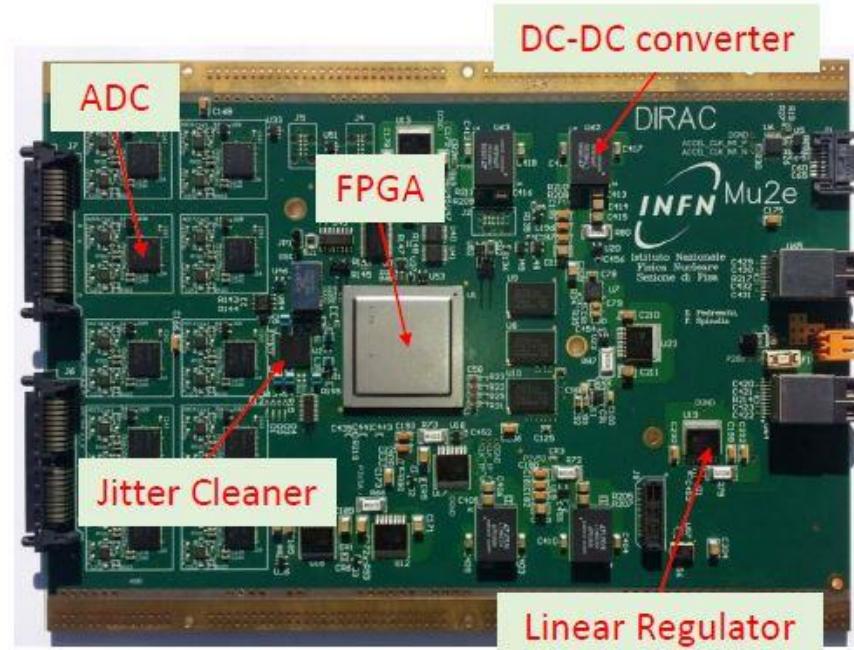
Componenti elettronici	Potenza dissipata [W]
➤ 10 ADC	5
➤ 1 FPGA	4
➤ 1 Jitter cleaner	0.8
➤ 4 DC-DC converters	7
➤ 6 Linear Regulator	20

The powers reported are the maximum reported on the components datasheet.

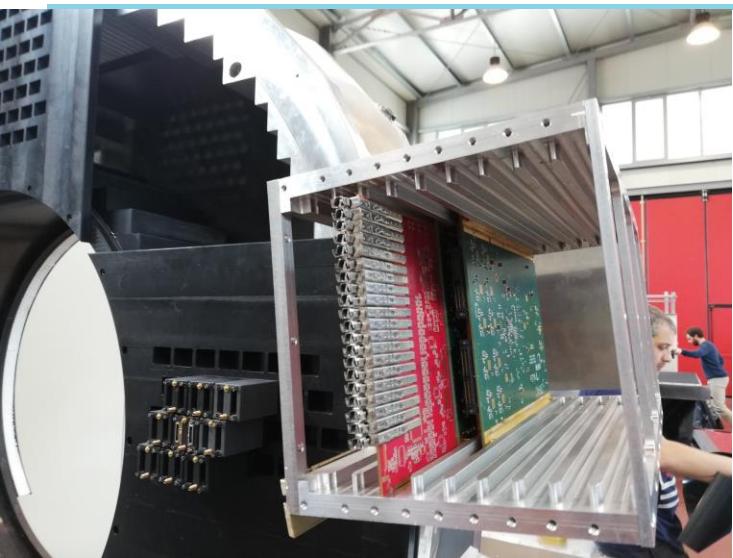
$$P_{diss}^{DIRAC} \approx 37W$$

$$P_{diss}^{INTERF} \approx 10W$$

$$P_{diss}^{Crate} \approx 423 W$$

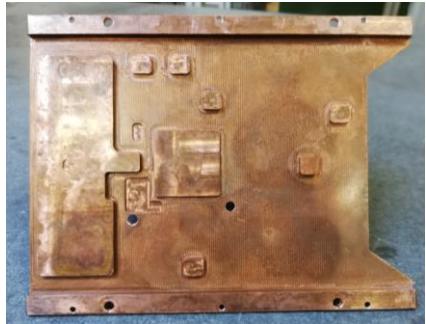


# Dirac board assembly and test.



# Crate design.

## Copper Plate



We prototype three copper plate in our machine shop. We are testing under vacuum with different TIM materials.



# Crate cooling test.

## Temperatures test

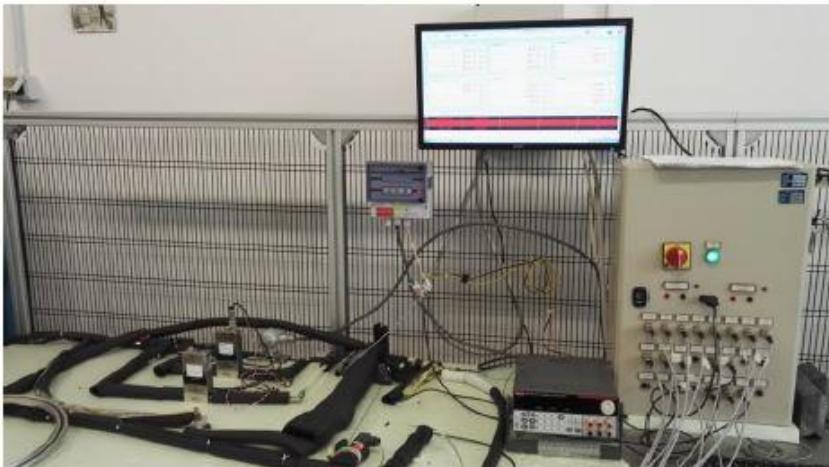


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### Test sequence.

- Vacuum vessel sealed.
- Vacuum level Ok.
- Chiller start flowing.
- Equilibrium reached.
- Data are taken.

25 temperature point has been measured



# Crate cooling test.

## Temperature test



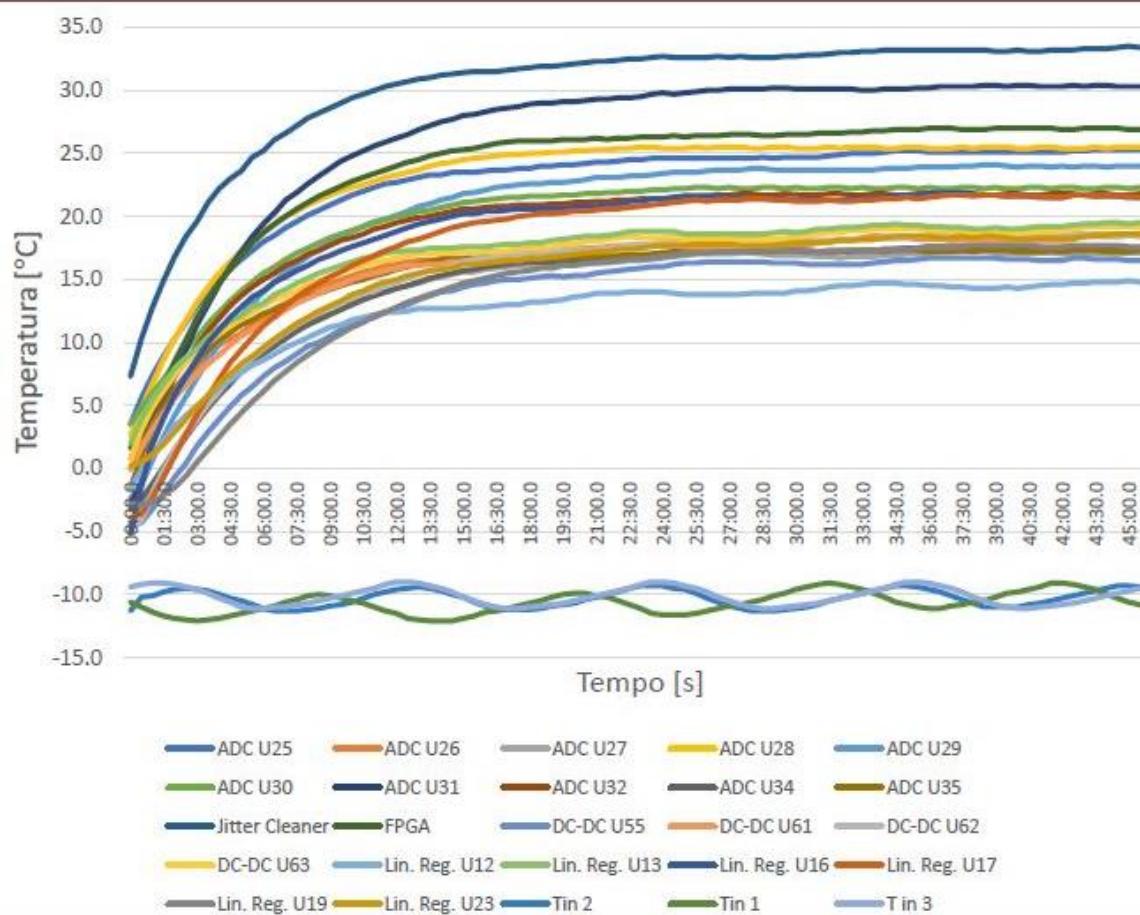
Fermilab



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### Results:

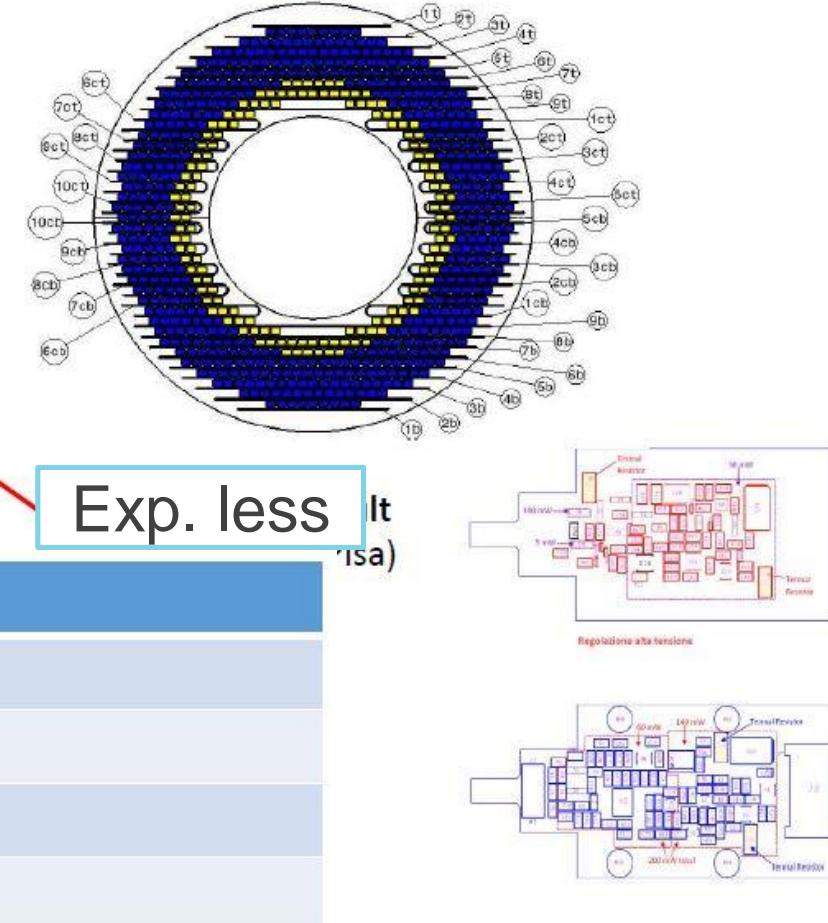
- Total measurement time 45 minutes
- State status reached in 20 minutes



# Summary of cooling.

## Heat to remove

Item	Contribute	Number	Total
Internal SiPMs (yellow)	0.69W for each SiPM	284 for each disk	196W for each disk
External SiPMs (blue)	0.23W for each SiPM	1064 for each disk	245W for each disk
FEE boards	0.355W for each board	1348 for each disk	479W for each disk
Digitizer	46.9W for each board	9 for each crate	422W for each crate
<b>TOTAL for both disks</b>			<b>10300W</b>



Exp. less  
It  
(isa)

Item	Mass flow
Front end	1.1kg/s for one disk
Digitizer	0.8kg/s for one disk
Total for one disk	1.9kg/s
<b>TOTAL for 2 disks</b>	<b>3.8kg/s</b>

# Aggiornamento sul raffreddamento del calorimetro.

## Cooling fluid: perfluoro-hexane: $C_6F_{14}$ as alternative to 35% glycol

### Advantages

boiling temperature

Lower viscosity ( $1.37 \cdot 10^{-3} \text{ Pa} \cdot \text{s}$ )

Higher density ( $1792 \text{ kg/m}^3$ )

Evaporate immediately and cleanly

Non toxic

### Drawbacks

Lower specific heat ( $982 \text{ J/kgK}$ )

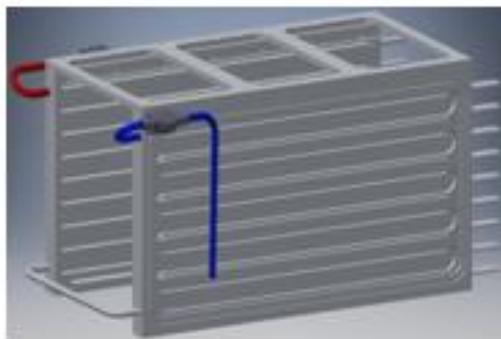
Lower thermal conductivity ( $6.62 \cdot 10^{-2} \text{ W/Km}$ )

Higher cost ( $65 \text{ $/kg}$ )

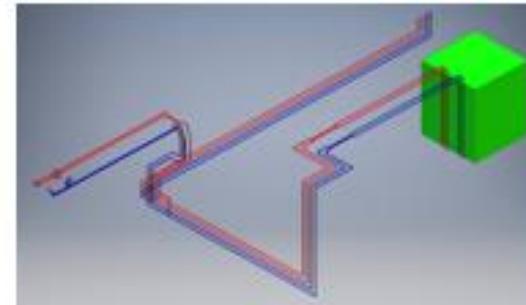
More probable leaks

# Aggiornamento sul raffreddamento del calorimetro.

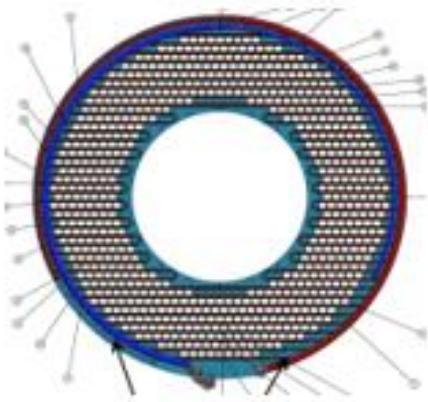
## Hydraulic volumes



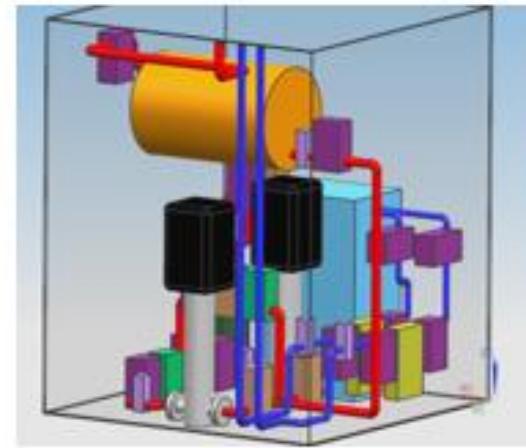
DAQ line:  
 $8 \cdot 10^{-3} m^3$



Routing lines:  
 $3.6 \cdot 10^{-2} m^3$



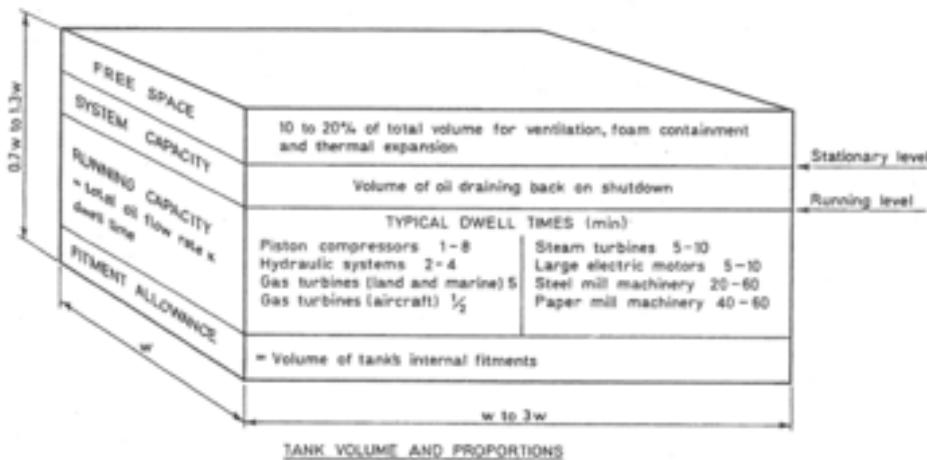
FEE line:  
 $3.27 \cdot 10^{-3} m^3$



Alcove:  
 $1.22 \cdot 10^{-1} m^3$

# Aggiornamento sul raffreddamento del calorimetro.

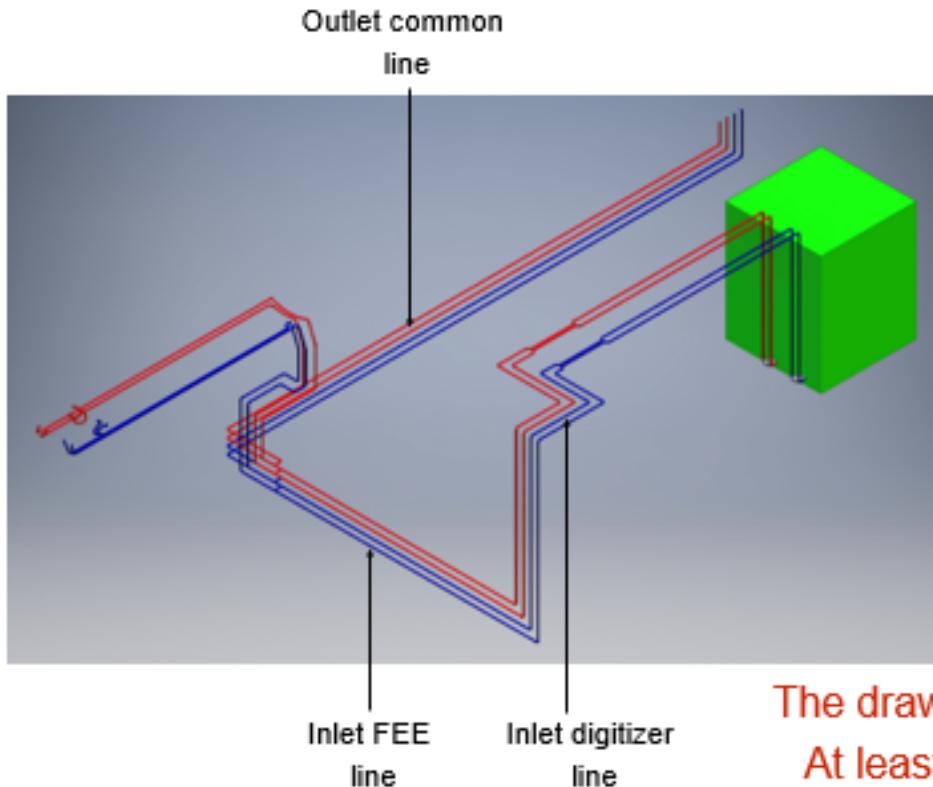
## Tank size



DWELL TIME	30 sec
FLOW RATE	4.5 kg/s
RUNNING CAPACITY	$0.075 \text{ m}^3$
SYSTEM CAPACITY	$0.3 \text{ m}^3$
TANK VOLUME	$0.413 \text{ m}^3$
MASS OF THE FLUID	740 kg
INITIAL FLUID COST	48.9 k\$

# Aggiornamento sul raffreddamento del calorimetro.

## Routing lines pressure losses

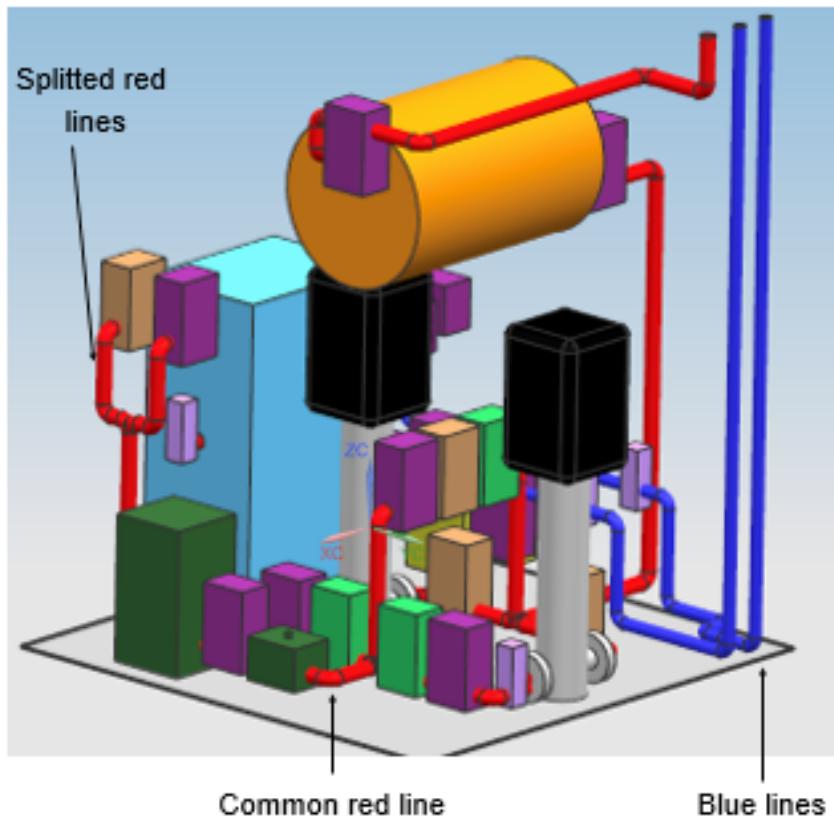


	Flow rate	Pressure loss
Inlet FEE line (1")	2.5 kg/s	1.56 bar
Inlet Digitizer line (1")	2 kg/s	0.98 bar
Outlet common line (1 1/2")	4.5 kg/s	0.34 bar
Total pressure loss		1.9 bar

The drawing needs to be updated.  
At least the outlet common line

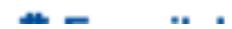
# Aggiornamento sul raffreddamento del calorimetro.

## Mechanical alcove pressure losses



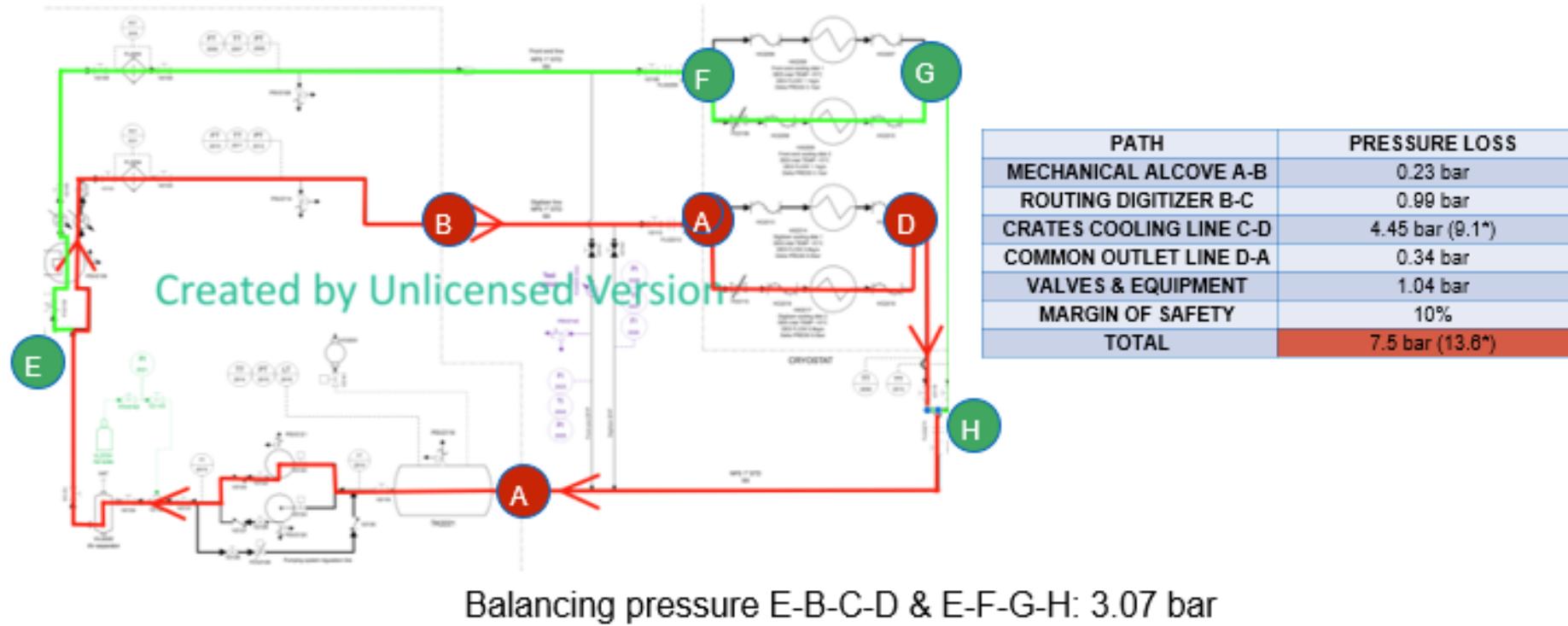
	Flow rate	Pressure loss
COMMON RED LINE (2")	4.5 kg/s	0.18 bar
SPLITTED RED LINES (1 1/2")	2 and 2.5 kg/s	0.01 bar
BLUE LINES (1 1/2")	2 and 2.5 kg/s	0.04 bar
Total pressure loss		0.23 bar

As soon as the lines get out of the chiller envelope, they match the routing pipes dimensions



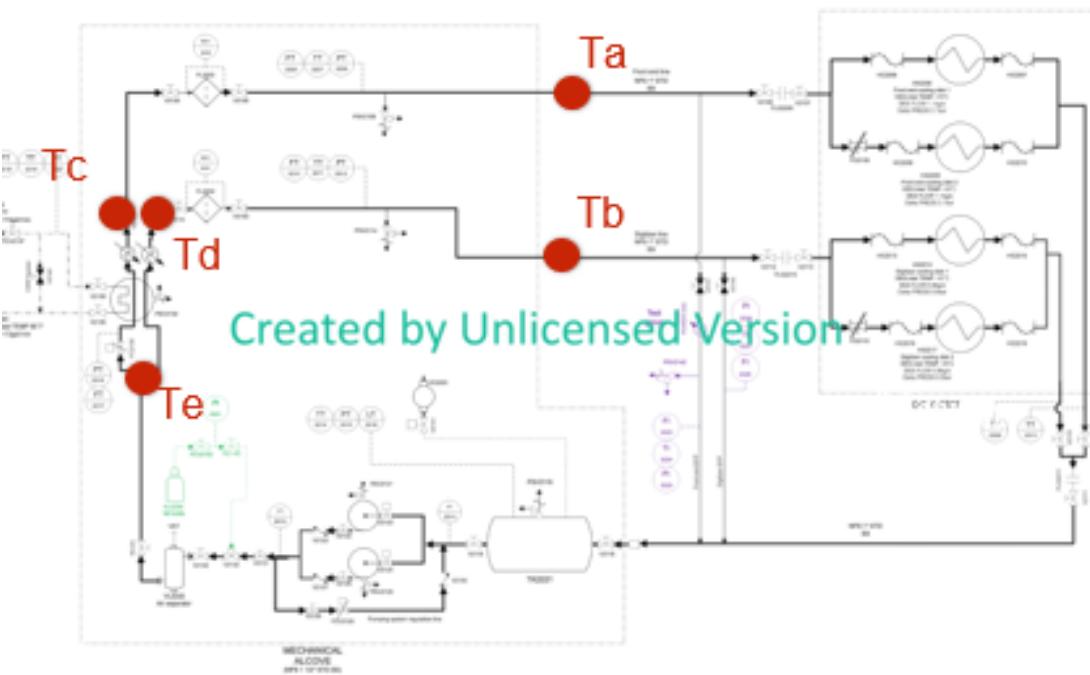
# Aggiornamento sul raffreddamento del calorimetro.

## Pressure losses summary



# Aggiornamento sul raffreddamento del calorimetro.

## Fluid temperatures

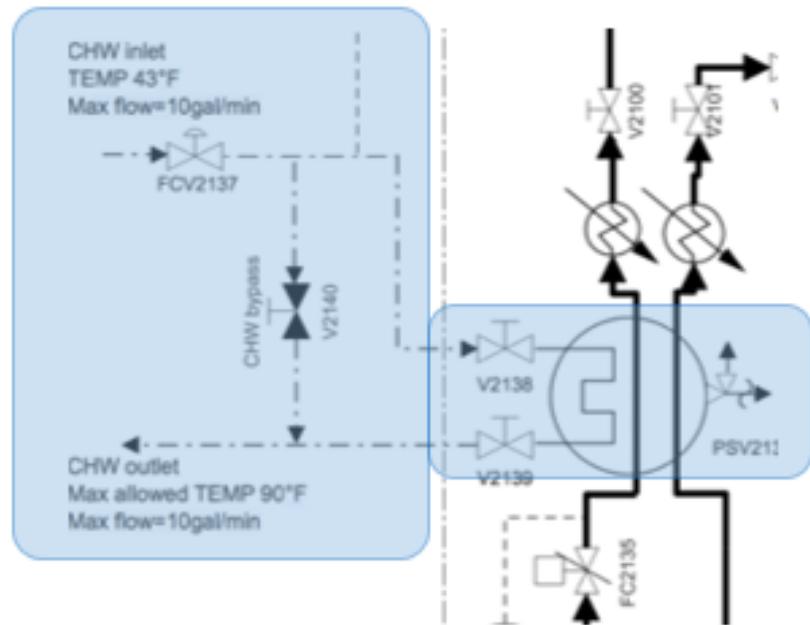


LOCATION	TEMPERATURE
Ta	-20.9 °C
Tb	-21.1 °C
Tc	-21 °C
Td	-21.2 °C
Averaged Tc/Td	-21.1 °C
Te	-18.5 °C
DeltaT chiller:	2.6 °C

The chiller must provide fluid at -21.1 °C of  
4.5 kg/s perfluorohexane

# Aggiornamento sul raffreddamento del calorimetro.

## Chiller requirements



- Chemically compatible with perfluorohexane
- 2 inlet and 2 outlet ports
- One channel crossed by 2 kg/s, and the other by 2.5 kg/s
- T entrance -21.1 °C, and outlet T -18.5 °C
- Able to absorb 10.8 kW
- Water cooled (preferably)
- Able to withstand a fluid pressure of 9 bar

# Aggiornamento sul raffreddamento del calorimetro.

## Open problems:

- 1) Max power available 25 Kwatt. Power needs to remove 10.8 Kwatt. Considering 2 Kwatt for pumping. We have 12 Kwatt that are marginal for the chiller efficiency and for the temperature control.  
May be we need to have a very efficient chiller (more expensive)  
We need to have to line at different temperature -26 degree C and -10 degree C.
- 2) Calorimeter temperatures control:  
Equilibrium temperatures it is very difficult to estimate with a good level of confidence. All cold part are thermally isolate for the calorimeter structure and from crystals, but small thermal flow are unavoidable. (like the cold SIPM toward the crystal). On the other end cables and outer surface are warm and irradiated toward the calorimeter. In this situation we need to have an active temperature control system.

# Aggiornamento sul cilindro interno di carbonio.

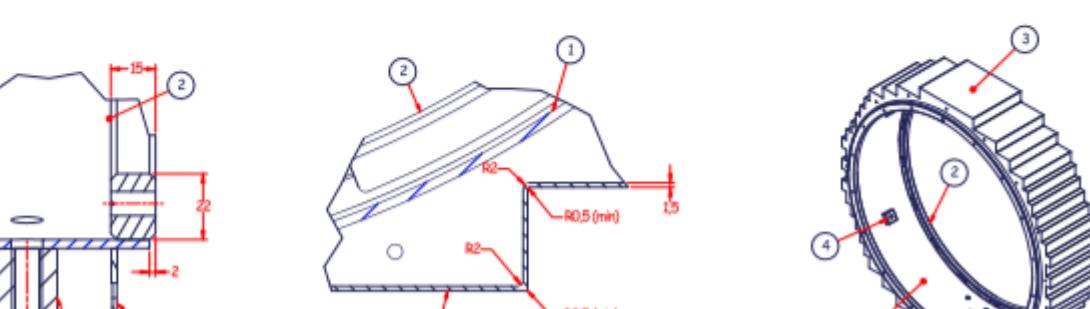
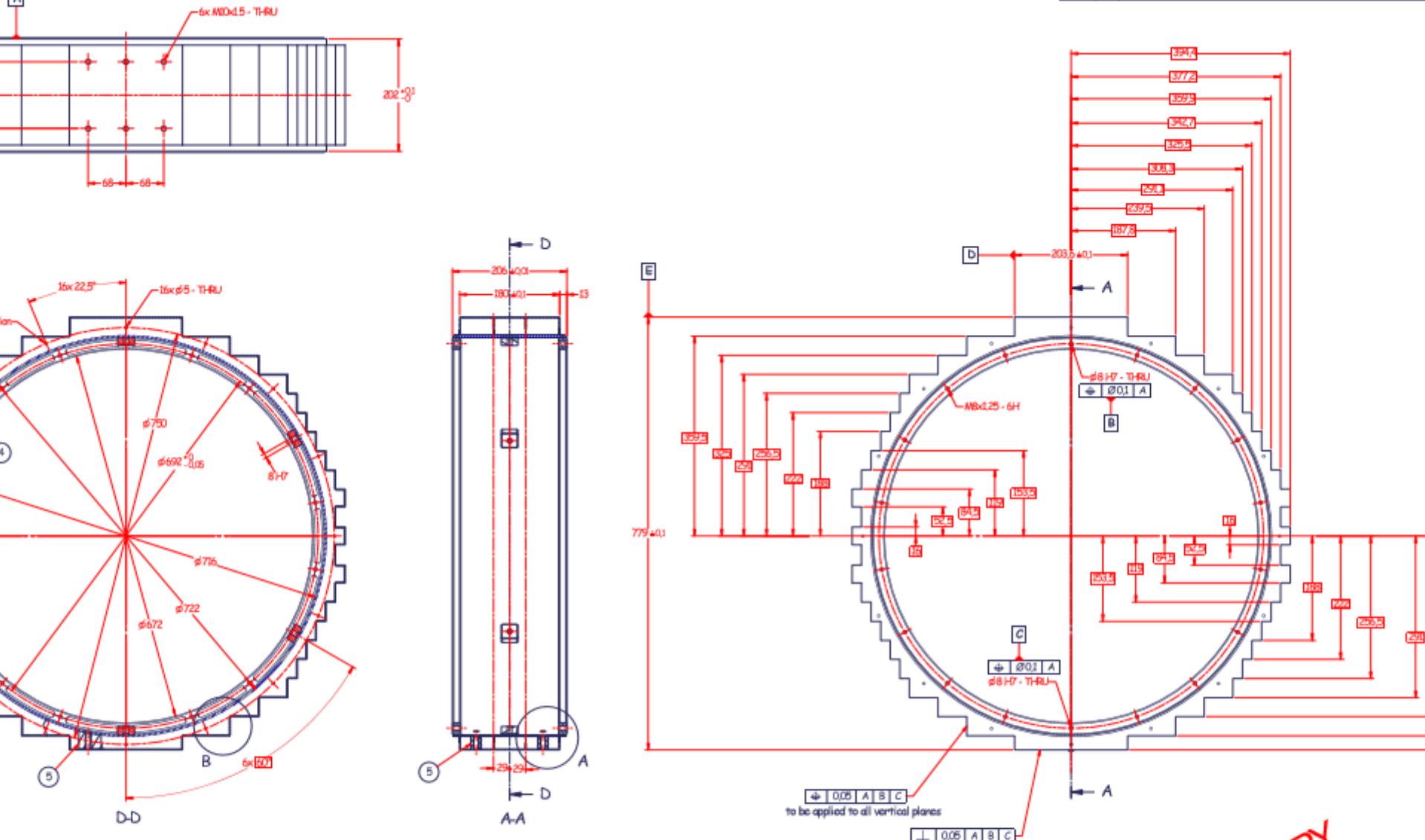
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Base solution: end rings aluminum CF inner cylinder, aluminum open cell foam, CF steps.

During the mechanical review was pointed on the problem to cut or machine the Aluminum foam without close the cell and contaminated the material. So we are searching a solution full carbon with no aluminum foam.

The company that has to manufacturing the carbon fiber component is CETMA at Brindisi.

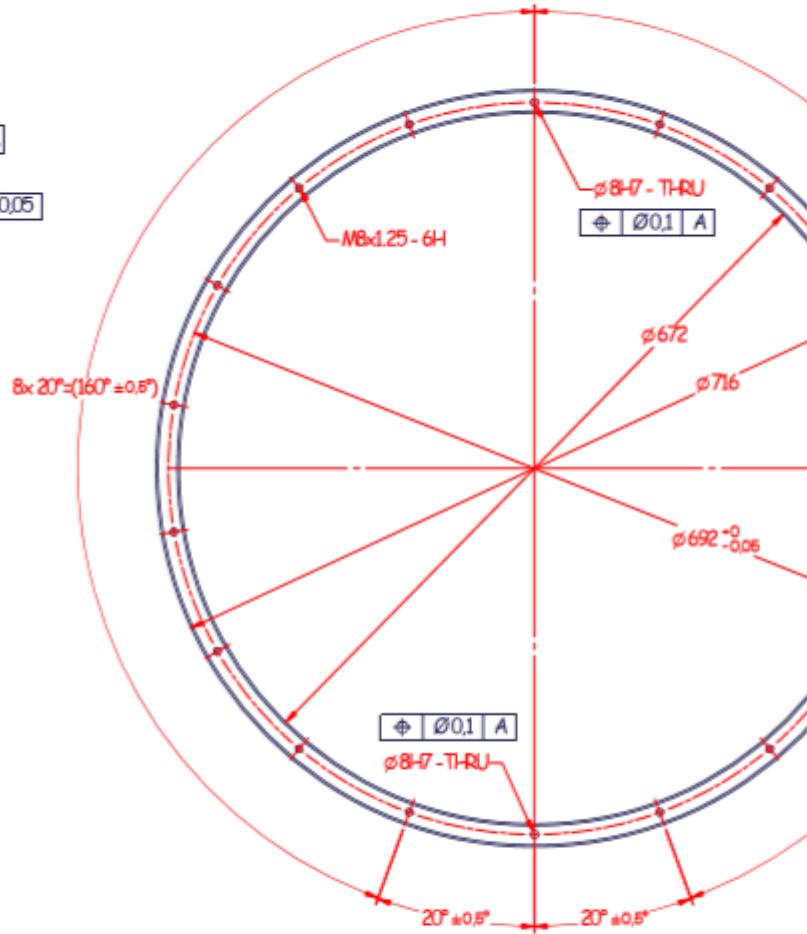
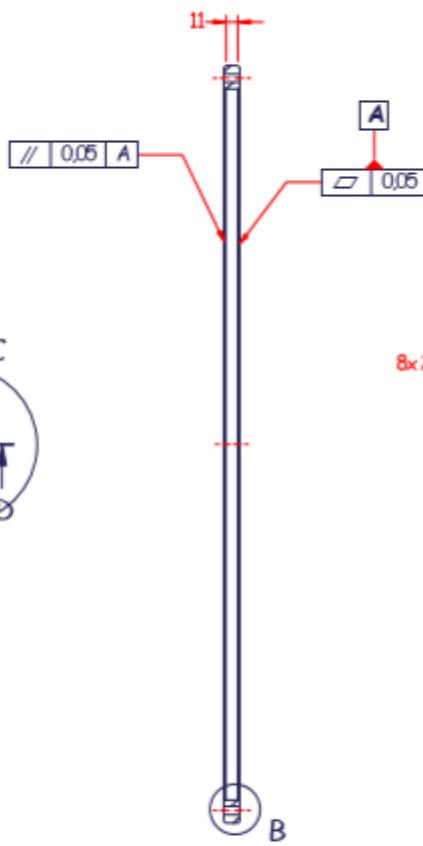
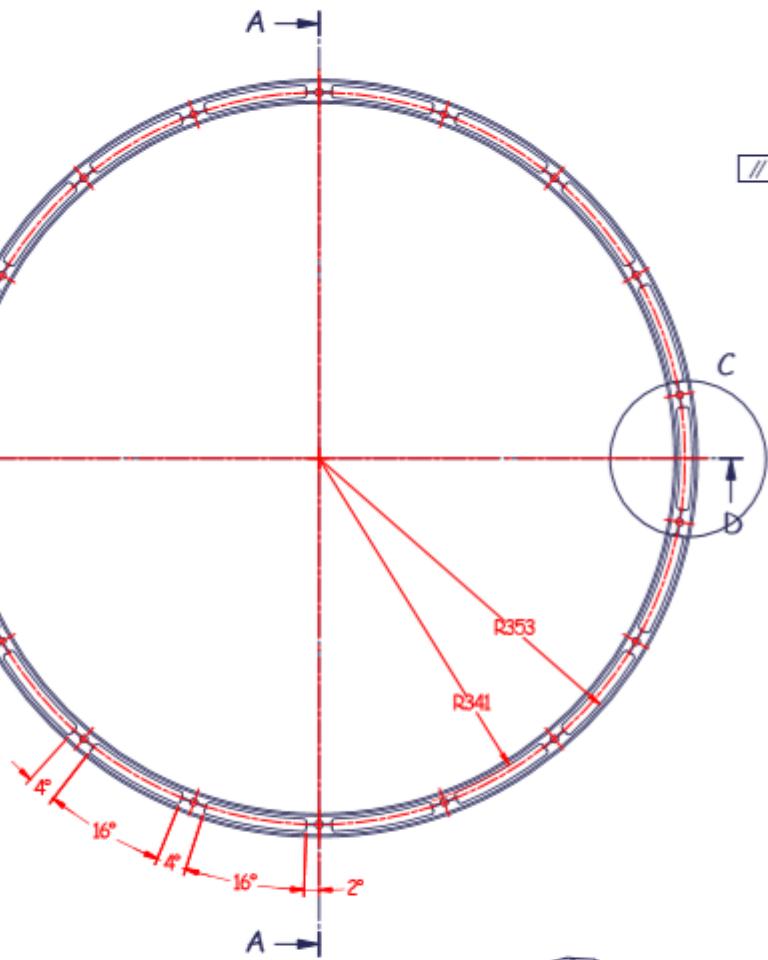
He has the carbon fiber pre-preg in house one mold to make the inner tube, It is placing the order for the two ends rings. They need to produced the mold for the steps and the assembly gluing tooling. A preliminary manufacturing and control steps has been made by us and revised by Cetma.



**PRELIMINARY  
-for information only-**

Bill of Materials	
LINE	CQTY
1	1
2	2
3	1
4	6
5	2
PART NUMBER	
1	Muze 08 00 00 - 01
2	Muze 08 00 00 - 02
3	Muze 08 00 00 - 03
4	Muze 08 00 00 - 05
5	Muze 08 00 00 - 06
DESCRIPTION	
1	Inner Ring
2	Reinforcement
3	Inner Step
4	Target Holder
5	Nog
QUANTITY	
1	Muze 08 00 00 - 01
1	Muze 08 00 00 - 02
1	Muze 08 00 00 - 03
6	Muze 08 00 00 - 05
2	Muze 08 00 00 - 06

D-D(1:4)



- Part to be free of burrs and sharp edges
- All material to be clean, degreased
- Any change must be authorized
- If in doubt, ask

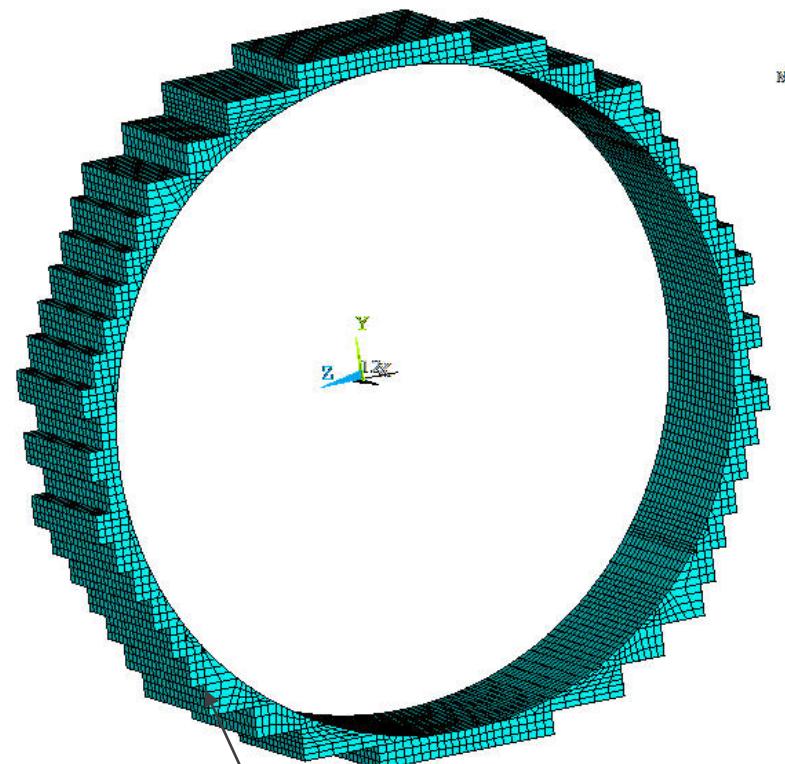
**PRELIMINARY**  
Information only

REF ID	REV	QTY	NOTE
UNASSY'D	00	2	

**INFN**

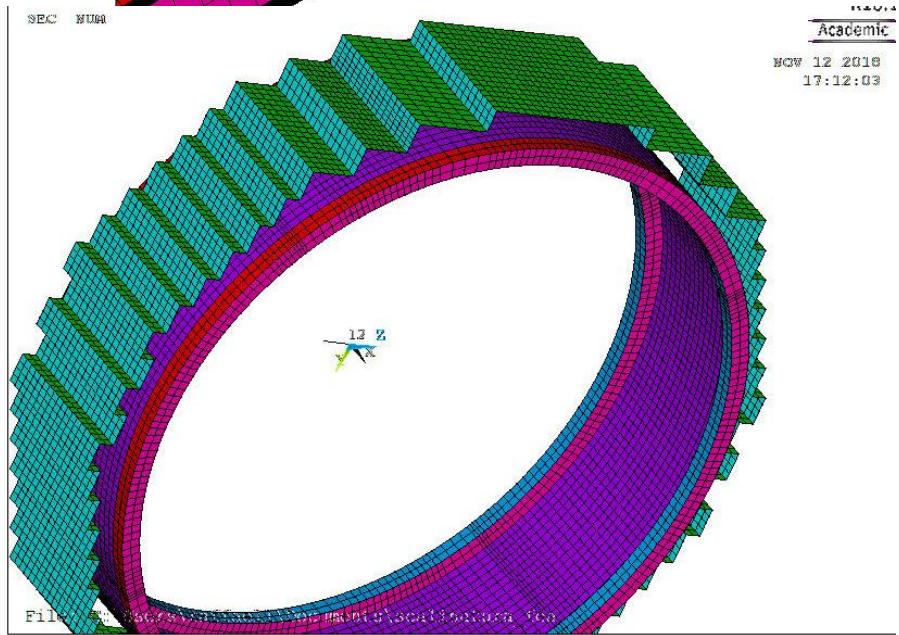
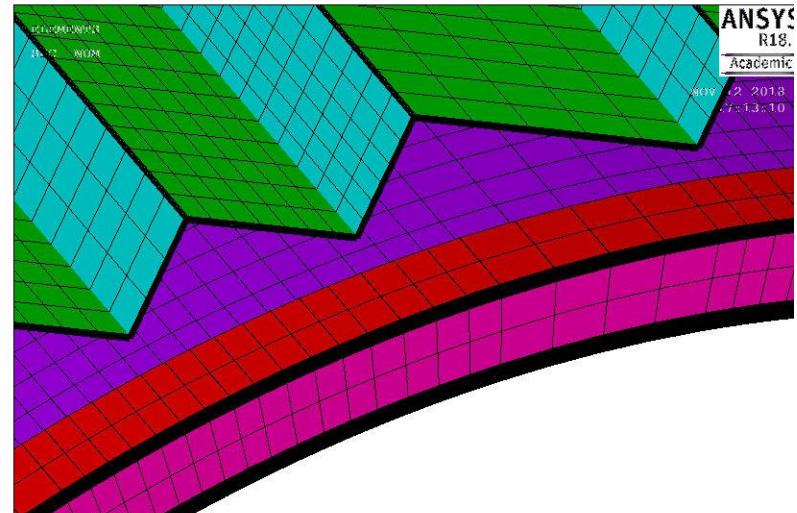
Mu

# Model with CF steps and Aluminum foam



EX	1E+008	GXY	1.99E+008
EY	1E+008	GYZ	1.99E+008
EZ	1E+008	GXZ	1.99E+008

Unit SI (Pa)



# Aluminum open cell Foam properties

## Physical Characteristics of Duocel® Aluminum Foam\* (8% Nominal Density 6101-T6)

Compression Strength	367 psi	(2.53 MPa)
Tensile Strength*	180 psi	(1.24 MPa)
Shear Strength*	190 psi	(1.31 MPa)
Modulus of Elasticity (Compression)*	$15 \times 10^3$ psi	(103.08 MPa)
Modulus of Elasticity (Tension)*	$14.6 \times 10^3$ psi	(101.84 MPa)
Shear Modulus	$2.9 \times 10^4$ psi	(199.95 MPa)
Vickers Pyramid Number	35 HV	
Specific Heat	.214 BTU/lb-°F	(.895 J/g-C)
Bulk Thermal Conductivity	3.4 BTU/ft-hr-F	(5.8 W/m-C)
Coefficient of Thermal Expansion (0-100°C)	$13.1 \times 10^{-6}$ in/in-F	( $23.58 \times 10^{-6}$ m/m-C)
Bulk Resistivity	$2.84 \times 10^{-5}$ ohm - in	( $7.2 \times 10^{-5}$ ohm - cm)
Melting Point	1220°F	(660°C)

Aluminum Foam Thermal conductivity

$$K_{\text{foam}} = 167 * 0.08 * 0.33 = 4.49 \text{ W/m C}$$

$$C_{\text{total}} = C_{\text{solid ligaments}} + C_{\text{gas}} + C_{\text{gas convection}} + C_{\text{radiant}}$$

Where

$C_{\text{solid ligaments}}$  = the conductivity of the three-dimensional array of solid ligaments or struts that form the foam structure. This term is also often referred to as the "bulk thermal conductivity" of the foam. In most applications, particularly for metal foams used as heat exchangers, this is the quantitatively largest and most thermally dominant of the four components and has the following simplified equation form:

$$C_{\text{solid ligaments}} = C_{\text{solid}} \times \text{relative density} \times .33$$

Where

$C_{\text{solid ligaments}}$  = direct thermal conductivity or bulk conductivity of the ligament array

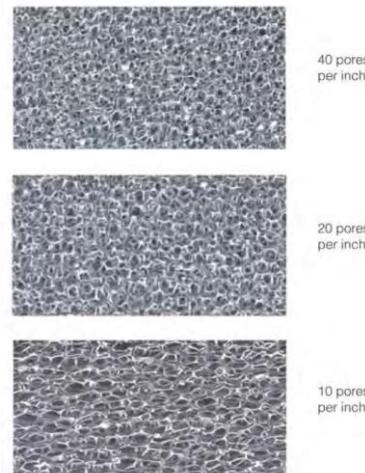
$C_{\text{solid}}$  = conductivity of the solid material of the struts

Relative Density = % relative density in decimal form, i.e. 10% = .1

.33 = coefficient representing the foam structure geometric or "tortuosity" factor.

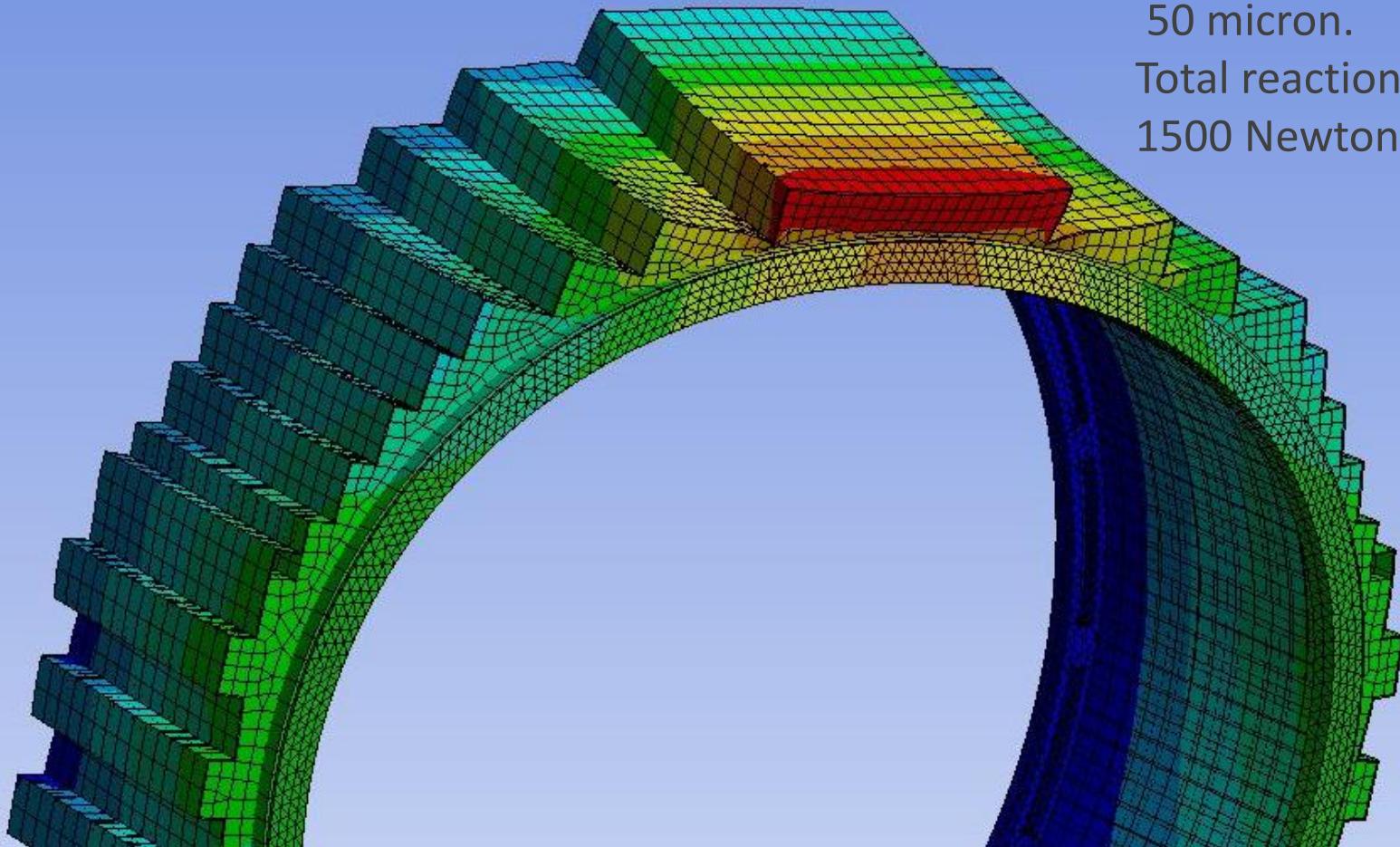
It should be noted that the .33 coefficient is derived both from conductivity tests and conceptual analysis wherein the foam can be analogized to a three-dimensional orthogonal pin fin array. In this case it is obvious that one third of the pins or pin mass are oriented in each of the orthogonal x, y, and z directions.

It should also be noted that this equation is somewhat simplified, but is reasonably accurate, slightly conservative, and is more easily understood from a conceptual standpoint than some of the empirical equations that have been developed from various tests.

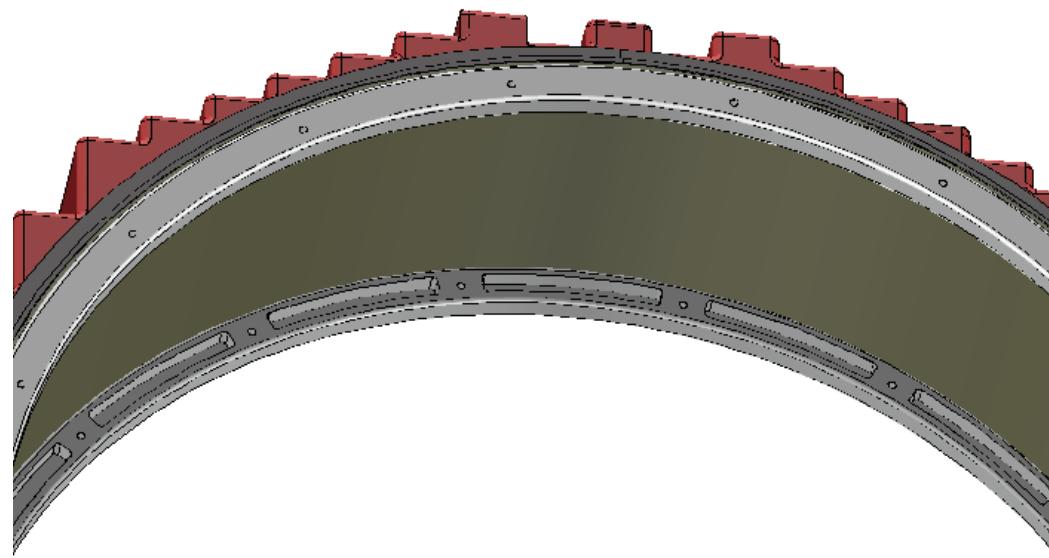
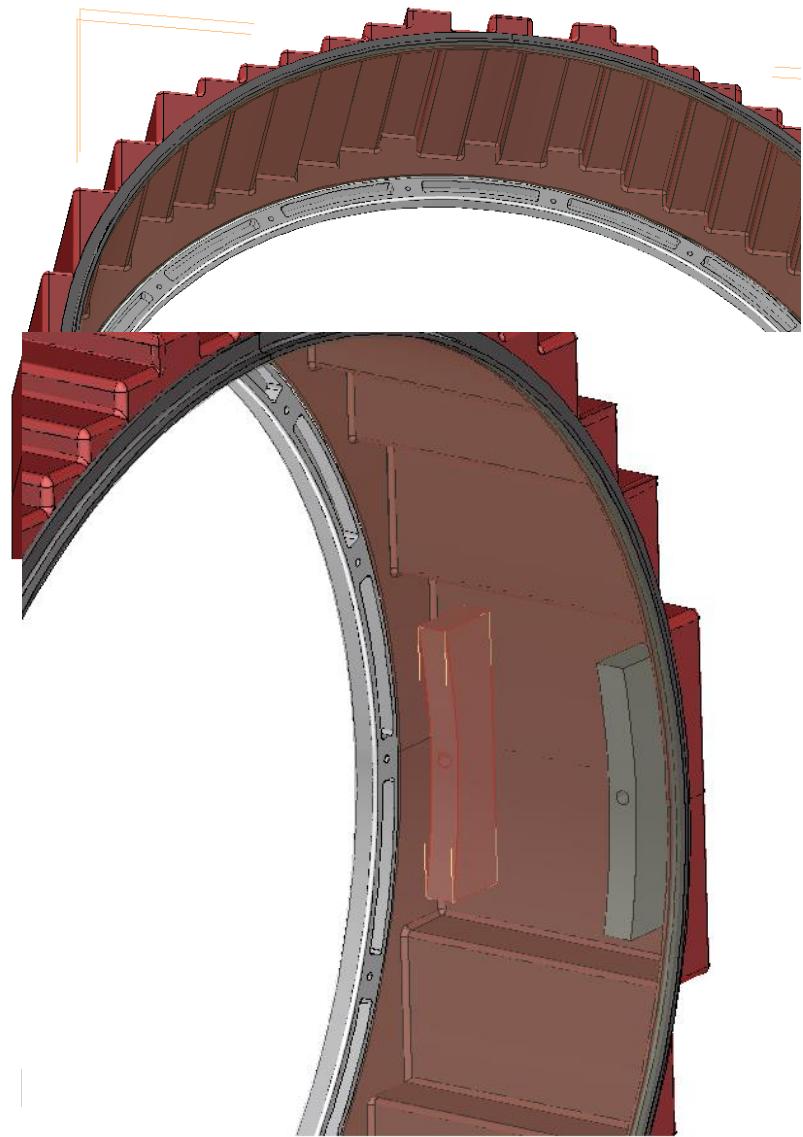


# Aluminum ends ring

Max  
displacement  
50 micron.  
Total reaction  
1500 Newton



# Aluminum ends ring full carbon



# Conclusion

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- Cooling:
- we need to have some iterations with the integration Fermilab group to verify that the new cooling specification are implemented on their own environmental.
- We need to qualify components during the production to verify their cooling performances.
- Carbon fiber components:
- We are not yet converging on mechanical solution for the inner cylinder that it is accepted by Cetma for the moment.